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- Stress Free
- Reworkable
- Electrically Conductive
- Epoxy Paste Adhesive
- 50 Micron Bondline Control

IDEAL FOR:

- Large Area Die
- Substrate and Component
- Reworkability
- Mismatched CTE's
- Controlled 50 Micron Bondline

DESCRIPTION:

ME8456-LV-GS002 is a lower viscosity version of ME8456. It is a reworkable, pure silver filled, electrically and thermally conductive epoxy paste adhesive which contains 2 mil diameter glass beads. It exhibits outstanding flexibility for bonding materials with highly mismatched CTE's (I.e., alumina to aluminum, silicon to copper).

It can be readily reworked from 80 to 100°C and is ideal for applications such as large area die attach and substrate attach because of its ability to bond materials with highly mismatched CTE's.

AVAILABILITY:

ME8456-LV-GS002 is available in syringes for automatic needle dispense applications or in jars. Both viscosity and thixotropic index can be modified to your specific needs.

APPLICATION PROCEDURES:

- (1) Thaw for 30 minutes before opening jar.
- (2) Dispense adhesive onto clean substrate.
- (3) Pre-bake dispensed adhesive open-face at 80°C for 30 to 60 minutes to achieve optimum bonding.
- (4) Cure using one of the recommended cure schedules.

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.
 The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

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PRIMA-SOLDER
ME8456-LV-GS002

TYPICAL PROPERTIES*

Electrical Resistivity (150°C/ 60 min)	4×10^{-4} ohm-cm
Dielectric Strength (Volts/mil)	N/A
Glass Transition Temp.(°C)	-20 ±10%
Current Carrying Capabilities	35 Amp/mm ²
Lap-Shear Strength	>1000 psi >6.9 N/mm ²
Device Push-off Strength	>2000 psi >13.8 N/mm ²
Hardness (Type)	80 (A) ±10%
Cured Density (gm/cc)	3.5 ±10%
Thermal Conductivity	55 Btu-in/hr-ft ² -°F ±10% 7.9 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	100 ±15%
Maximum Continuous Operation Temp. (°C)	<150
Pot Life	
Avg. Viscosity(0.5 rpm, 25°C) (Brookfield DV-1,spindle CP51)	50,000-90,000 cp ±20%
Thixotropic Index	

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CURE SCHEDULES:

<u>Temperature</u>	<u>Time</u>	<u>Pressure</u>
80°C	8 hr	
100°C	4 hr	
125°C	2 hr	
150°C	1 hr	

SHELF LIFE:

<u>Storage temperature</u>	<u>Shelf Life</u>
-40°C	1 yr
POT LIFE	5 Days @ 25°C